

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A manufacturing method of a light emitting device including a pixel portion provided with a plurality of light emitting elements having a first electrode, an organic compound layer in contact with a top portion of the first electrode, and a second electrode in contact with a top portion of the organic compound layer, between a pair of substrates, at least one of which is transparent, the manufacturing method of a light emitting device comprising the steps of:

forming a pixel portion over one of the substrates;

figuring a first sealing material having a bar shape on the other substrate;

applying a plurality of drops of a second sealing material having lower viscosity than the first sealing material to a region surrounded by the first sealing material so that an amount of drops differs depending on a region to be applied to; and

pasting the pair of substrates so that the first sealing material is arranged to surround the pixel region, and a space between at least a pair of the first sealing materials is filled with the second sealing material,

wherein the second sealing material is applied at least to a central part of the pixel portion and to a position surrounding the central part.

2. (Currently Amended) A manufacturing method of a light emitting device according to claim 1, ~~wherein the second sealing material is applied at least to a central part of a pixel portion and to a position surrounding the central part with a constant distance therefrom; and~~ an amount of the second sealing material applied to the central part is larger than an amount applied to the position surrounding the central part.

3. (Original) A manufacturing method of a light emitting device according to claim 1, wherein the first sealing material has opening portions at least at four corners.

4. (Original) A manufacturing method of a light emitting device according to claim 1, wherein the first sealing material includes a spacer for maintaining a gap between a pair of substrates.

5. (Original) A manufacturing method of a light emitting device according to claim 1, wherein the second sealing material is exposed at the opening portion, and a peripheral border of the exposed second sealing material is curved.

6. (Original) A manufacturing method of a light emitting device according to claim 1, wherein the second sealing material is exposed at the opening portion, and peripheral border of the exposed second sealing material protrudes from the opening portion.

7. (Currently Amended) A manufacturing method of a light emitting device including a pixel portion provided with a plurality of light emitting elements having a first electrode, an organic compound layer in contact with a top portion of the first electrode, and a second electrode in contact with a top portion of the organic compound layer, between a pair of substrates, one of which is transparent, the manufacturing method of a light emitting device comprising the steps of:

forming a pixel portion on one of the substrates;

figuring a first sealing material having a bar shape on the other substrate;

applying a plurality of drops of a second sealing material having lower viscosity than the first sealing material to a region surrounded by the first sealing material so that an amount of drops differs depending on a region to be applied to;

filling a space between the first sealing materials facing one another, by

spreading the second sealing material under pressure in the case where a pair of the substrates is pasted together so that the pixel region is surrounded by the first sealing material; and

curing the first sealing material and the second sealing material,

wherein the second sealing material is applied at least to a central part of the pixel portion and to a position surrounding the central part.

8. (Original) A manufacturing method of a light emitting device according to claim 7, wherein the curing of the first sealing material and the second sealing material is performed by exposure to ultraviolet radiation or by heat.

9. (Original) A manufacturing method of a light emitting device according to claim 7, wherein a pair of the substrates is divided vertically to the first sealing material after curing the first sealing material and the second sealing material.

10.-16. (Canceled)

17. (Currently Amended) A manufacturing method of a light emitting device comprising the steps of :

forming a pixel portion over a first substrate;

forming a first sealing material having a bar shape on a second substrate;

applying a plurality of drops of a second sealing material having lower viscosity than the first sealing material to a region surrounded by the first sealing material so that an amount of drops differs depending on a region to be applied to; and

pasting the pair of substrates so that the first sealing material is arranged to surround the pixel region, and a space between at least a pair of the first sealing materials is filled with the second sealing material,

wherein the second sealing material is applied at least to a central part of the

pixel portion and to a position surrounding the central part.

18. (Currently Amended) A manufacturing method of a light emitting device comprising the steps of :

forming a pixel portion over a first substrate;

forming a first sealing material having a bar shape on a second substrate;

applying a second sealing material having lower viscosity than the first sealing material to a first region and a second region which are surrounded by the first sealing material so that an amount of drops to the first region is larger than that to the second region; and

pasting the pair of substrates so that the first sealing material is arranged to surround the pixel region, and a space between at least a pair of the first sealing materials is filled with the second sealing material,

wherein the second sealing material is applied at least to a central part of the pixel portion and to a position surrounding the central part.

19. (New) A manufacturing method of a light emitting device according to claim 7, wherein an amount of the second sealing material applied to the central part is larger than an amount applied to the position surrounding the central part.

20. (New) A manufacturing method of a light emitting device according to claim 17, wherein an amount of the second sealing material applied to the central part is larger than an amount applied to the position surrounding the central part.

21. (New) A manufacturing method of a light emitting device according to claim 18, wherein an amount of the second sealing material applied to the central part is larger than an amount applied to the position surrounding the central part.